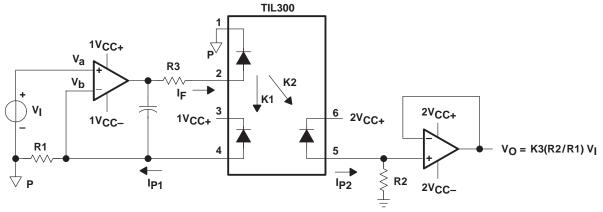
- ac or dc Signal Coupling
- Wide Bandwidth . . . > 200 kHz
- High Transfer-Gain Stability . . . ±0.05%/°C
- 3500 V Peak Isolation
- UL Approval Pending
- Applications
 - Power-Supply Feedback
 - Medical-Sensor Isolation
 - Opto Direct-Access Arrangement (DAA)
 - Isolated Process-Control Transducers

NC - No internal connection

description

The TIL300 precision linear optocoupler consists of an infrared LED irradiating an isolated feedback photodiode and an output photodiode in a bifurcated arrangement. The feedback photodiode captures a percentage of the flux of the LED and generates a control signal that can be used to regulate the LED drive current. This technique is used to compensate for the nonlinear time and temperature characteristics of the LED. The output-side photodiode produces an output signal that is linearly proportional to the servo-optical flux emitted from the LED.

A typical application circuit (shown in Figure 1) uses an operational amplifier as the input to drive the LED. The feedback photodiode sources current through R1, which is connected to the inverting input of the input operational amplifier. The photocurrent I_{P1} assumes a magnitude that satisfies the relationship $I_{P1} = V_I/R1$. The magnitude of the current is directly proportional to the LED current through the feedback transfer gain $K1(V_I/R1 = K1 \times I_F)$. The operational amplifier supplies LED current to produce sufficient photocurrent to keep the node voltage V_h equal to node voltage V_a



NOTES: A. K1 is servo current gain, the ratio of the feedback photodiode current (IP1) to the input LED current (IF), i.e. K1 = IP1/IF.

- B. K2 is forward gain, the ratio of the output photodiode current (I_{P2}) to the input LED current (I_{F}), i.e. $K2 = I_{P2}/I_{F}$.
- C. K3 is transfer gain, the ratio of the forward gain to the servo gain, i.e. K3 = K2/K1.

Figure 1. Typical Application Circuit



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SOES019A - OCTOBER 1995 - REVISED JULY 1996

Terminal Functions

TERMINAL		1/0	DESCRIPTION
NAME	NO.	1/0	DESCRIPTION
LEDK	1		LED cathode
LEDA	2		LED anode
PDK1	3		Photodiode 1 cathode
PDA1	4		Photodiode 1 anode
PDA2	5		Photodiode 2 anode
PDK2	6		Photodiode 2 cathode
NC	7		No internal connection
NC	8		No internal connection

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

F	n	٦i	t	h	4	r
_			U	Ľ	◡	ı

Continuous total power dissipation (see Note 1)	160 mW
Input LED forward current, I _F	60 mA
Surge current with pulse width < 10 μs	250 mA
Reverse voltage, V _R	5 V
Reverse current, I _R	10 μΑ

Detector

Continuous power dissipation (see Note 2)	 50 mW
Reverse voltage. Vp	 50 V

Coupler

Couple	
Continuous total power dissipation (see Note 3)	210 mW
Storage temperature, T _{stq} –55	°C to 150°C
Operating temperature, T _A –55	°C to 100°C
Input-to-output voltage	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Derate linearly from 25°C at a rate of 2.66 mW/°C.
 - 2. Derate linearly from 25°C at a rate of 0.66 mW/°C.
 - 3. Derate linearly from 25°C at a rate of 3.33 mW/°C.

electrical characteristics at $T_A = 25$ °C

Emitter

PARAMETER		С	CONDITIONS			MAX	UNIT
٧F	Forward voltage	IF = 10 mA			1.25	1.50	V
	Temperature coefficient of V _F				-2.2		mV/°C
I_R	Reverse current	V _R = 5 V				10	μΑ
t _r	Rise time	$I_F = 10 \text{ mA},$	$\Delta I_F = 2 \text{ mA}$		1		μs
tf	Fall time	I _F = 10 mA,	$\Delta I_F = 2 \text{ mA}$		1		μs
Ci	Junction capacitance	$V_{F} = 0,$	f = 1 MHz		15		pF

Detector

PARAMETER		CO	MIN	TYP [†]	MAX	UNIT	
I _{DK} †	Dark current	V _R = 15 V,	IF = 0			25	nA
	Open circuit voltage	I _F = 10 mA			0.5		V
los	Short circuit current limit	I _F = 10 mA			80		μΑ
Ci	Junction capacitance	$V_{F} = 0$,	f = 1 MHz		12		pF

Coupler

	PARAMETER		CONDITION	CONDITIONS			MAX	UNIT
174 [†]	Comic current asia			I _F = 1 mA	0.3%	0.7%	1.5%	
K1‡	<1‡ Servo current gain			IF = 10 mA	0.5%	1.25%	2%	
K2§	Forward current gain	rword current goin		I _F = 1 mA	0.3%	0.7%	1.5%	
K23	Torward current gain	_	Detector bias	$I_F = 10 \text{ mA}$	0.5%	1.25%	2%	
		TIL300	voltage = −15 V	$I_F = 1 \text{ mA}$	0.75	1	1.25	
кз¶	Transfer gain	TILSOU		I _F = 10 mA	0.75	1	1.25	
K91	Transier gain	TIL300A]	IF = 1 mA	0.9	1	1.10	
				I _F = 10 mA	0.9	1	1.10	
	Coin tomporature coefficient	K1/K2	J= - 10 mΛ	= -10 mA		-0.5	%/°C	
	Gain temperature coefficient	K3	I _F = 10 mA		±0.005		76/ C	
.Vo#	Transfer gain linearity		I _F = 1 to 10 mA			±0.25%		
∆K3 [#]	Transier gain inteanty		$I_F = 1$ to 10 mA,	$T_A = 0 \text{ to } 75^{\circ}\text{C}$		±0.5%		
BW	Bandwidth		$I_F = 10 \text{ mA},$ $I_F(MODULATION) = \pm 2 \text{ mA}$	$R_L = 1 \text{ k}\Omega$,		200		kHz
t _r	Rise time		$I_F = 10 \text{ mA},$ $I_F(MODULATION) = \pm 2 \text{ mA}$	$R_L = 1 \text{ k}\Omega$,		1.75		μs
t _f	Fall time		$I_F = 10 \text{ mA},$ $I_F(MODULATION) = \pm 2 \text{ mA}$	$R_L = 1 k\Omega$,		1.75		μs
v _{iso} †	Peak Isolation voltage		I _{IO} = 10 μA, time = 1 minute	f = 60 Hz	3535		·	V

[†]This symbol is not currently listed within EIA or JEDEC standards for semiconductor symbology.



[‡] Servo current gain (K1) is the ratio of the feedback photodiode current (I_{P1}) to the input LED current (I_F) current (I_F), i.e. K1 = I_{P1}/I_F.

[§] Forward gain (K2 is the ratio of the output photodiode current (Ip2) to the input LED current (Ip), i.e. K2 = Ip2/Ip.

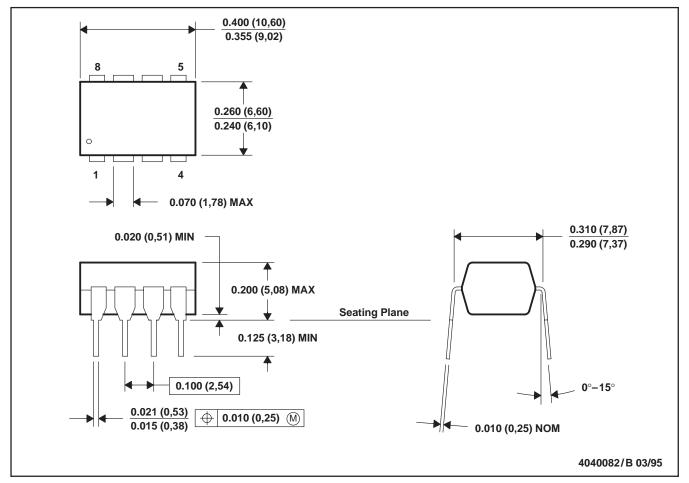
[¶] Transfer gain (K3) is the ratio of the forward gain to the servo gain, i.e. K3 = K2/K1.

[#] Transfer gain linearity (ΔK3) is the percent deviation of the transfer gain K3 as a function of LED input current (I_F) or the package temperature.

MECHANICAL DATA

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001



PACKAGE OPTION ADDENDUM

8-Apr-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TIL300	OBSOLETE	PDIP	N	8	TBD	Call TI	Call TI
TIL300A	OBSOLETE	PDIP	N	8	TBD	Call TI	Call TI
TIL300ADCS	OBSOLETE	OPTO	DCS	8	TBD	Call TI	Call TI
TIL300DCS	OBSOLETE	OPTO	DCS	8	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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